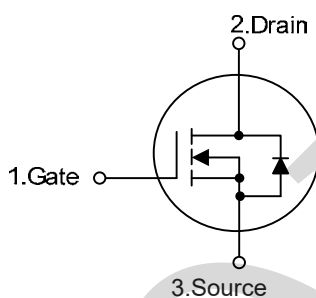
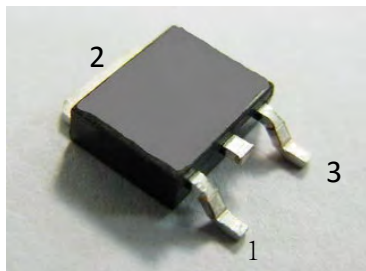


Trench N-channel Power MOSFET

MSR4R6N03D

TO-252



V_{DS}	30	V
$R_{DS(on),TYP@ V_{GS}=10V}$	3.0	m Ω
I_D	80	A

Features

- 1、 Low on – resistance
- 2、 Package TO-252
- 3、 TrenchFET Power MOSFET

Applications

- 1、 Load Switch for Portable Devices
- 2、 DC/DC Converter

Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	30	V
V_{GS}	Gate-Source voltage	± 20	V
I_S	Diode continuous forward current	$T_C = 25^\circ\text{C}$	--
I_D	Continuous drain current @ $V_{GS}=10V$	$T_C = 25^\circ\text{C}$	80
		$T_C = 100^\circ\text{C}$	60
I_{DM}	Pulse drain current tested ①	$T_C = 25^\circ\text{C}$	300
E_{AS}	Avalanche energy, single pulsed ②	52	mJ
P_D	Maximum power dissipation	$T_C = 25^\circ\text{C}$	85
T_{STG}, T_J	Storage and Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2.1	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	$^{\circ}\text{C}/\text{W}$

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Static Electrical Characteristics @ $T_j=25^{\circ}\text{C}$ (unless otherwise stated)

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	--	2.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance ④	$V_{GS}=10V, I_D=30A$	--	3.0	4.5	m Ω
		$V_{GS}=4.5V, I_D=20A$	--	5.0	8.0	m Ω

Dynamic Electrical Characteristics @ $T_j = 25^{\circ}\text{C}$ (unless otherwise stated)

C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V$, $f=1\text{MHz}$	--	2200	--	pF
C_{oss}	Output Capacitance		--	311	--	pF
C_{rss}	Reverse Transfer Capacitance		--	210	--	pF
g_{fs}	Forward Transconductance	$V_{DS} = 5V, I_D = 10A$	20	--	--	S
$Q_g(10V)$	Total Gate Charge	$V_{DS}=15V, I_D=30A$, $V_{GS}=10V$	--	51	--	nC
Q_{gs}	Gate-Source Charge		--	14	--	nC
Q_{gd}	Gate-Drain Charge		--	11	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	V _{DS} =15V, V _{GS} =10V, R _G =3.0Ω, I _D =30A	--	20	--	ns
Tr	Turn-on Rise Time		--	15	--	ns
Td(off)	Turn-Off Delay Time		--	60	--	ns
Tf	Turn-Off Fall Time		--	10	--	ns

Source -Drain Diode Characteristics @T_J = 25°C (unless otherwise stated)

V _{SD}	Forward on voltage	I _{SD} =1A, V _{GS} =0V	--	--	1.2	V
I _S	Maximun Body-Diode Continuous Current		--	--	80	A
I _{SM}	Maximun Body-Diode Pulsed Current(Note 4)		--	--	300	A

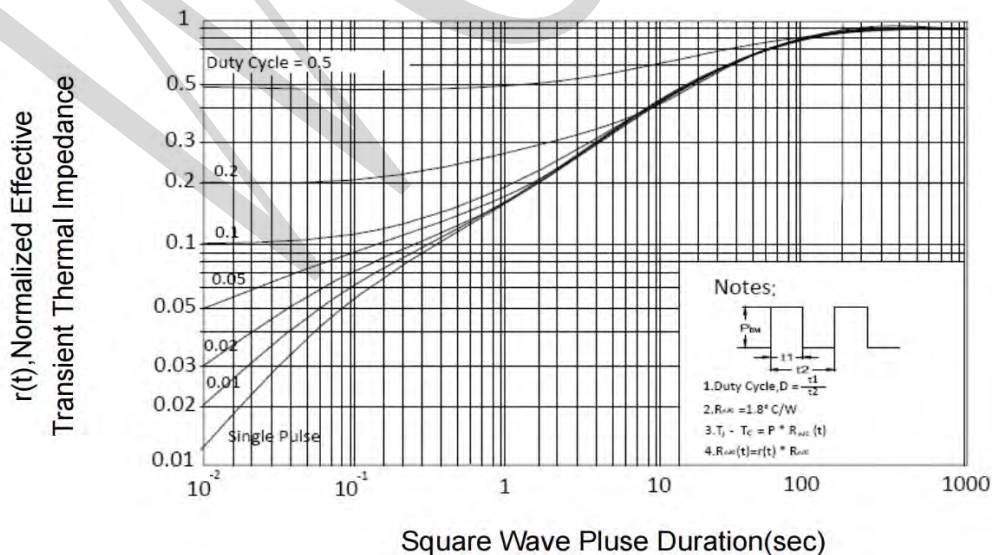
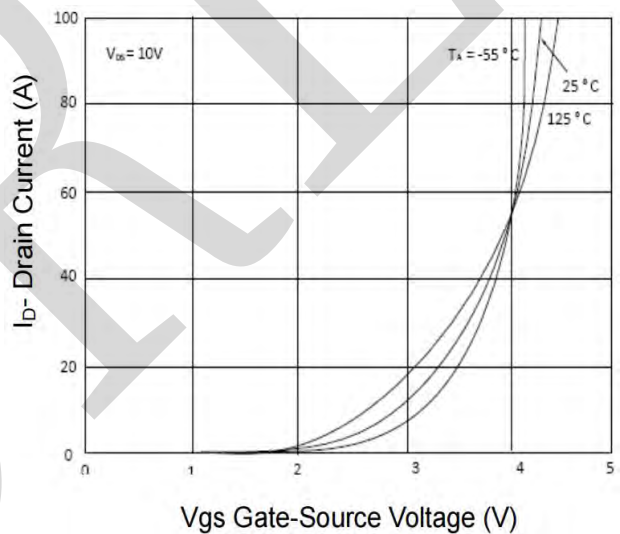
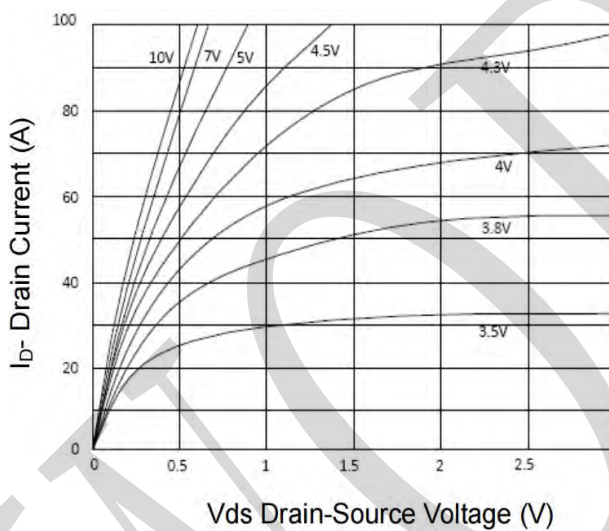
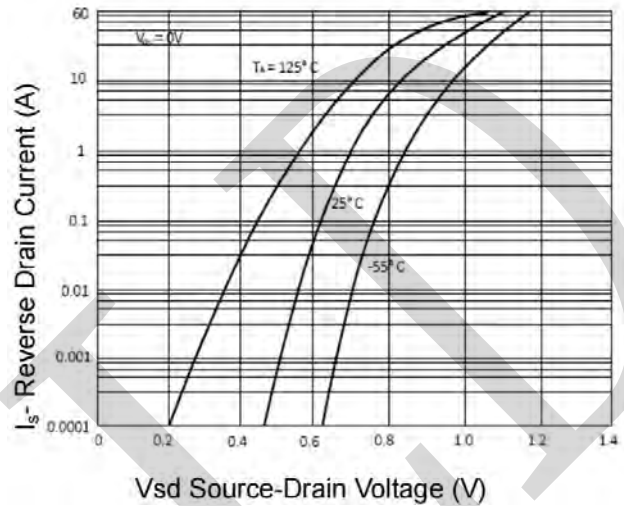
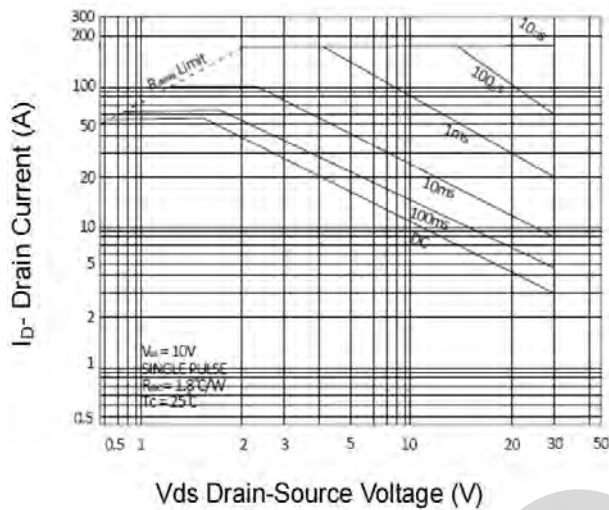
NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = 9A, V_{GS} = 10V. Part not recommended for use above this value

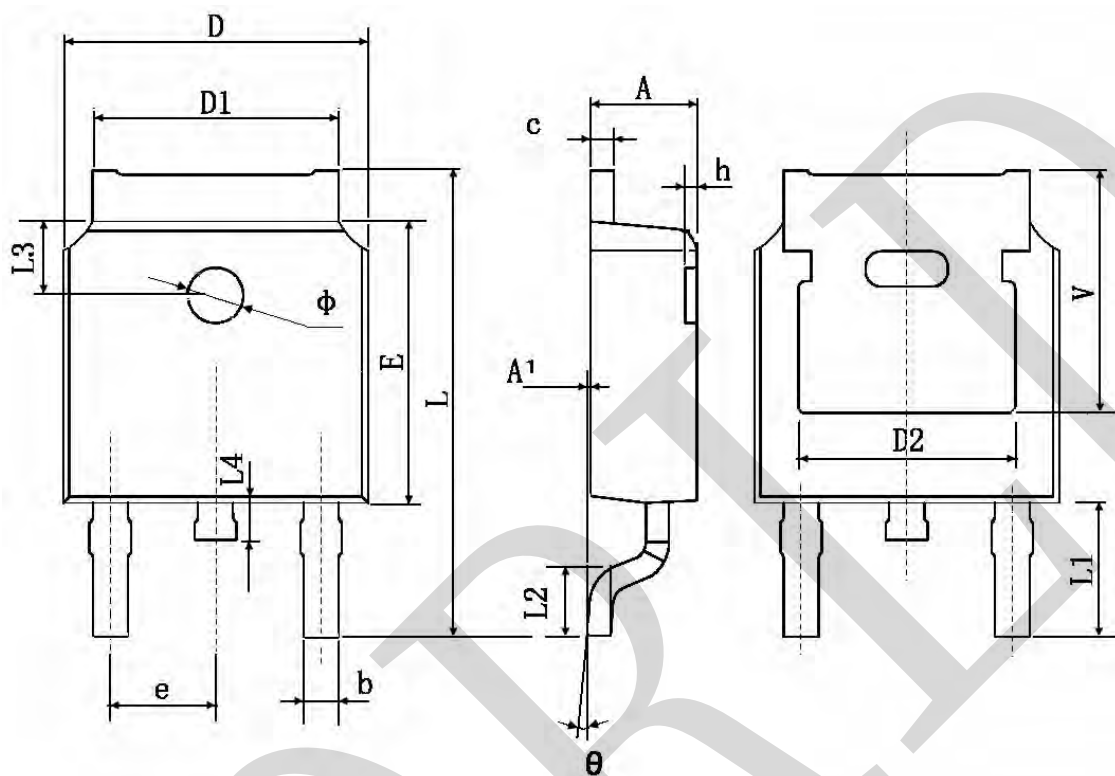
③ The power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C.

④ Pulse width ≤ 300μs; duty cycles ≤ 2%.

Typical Characteristics



PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	